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(54) HIGH-FREQUENCY PACKAGE

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a high-frequency package which is equipped with an antenna element and a high-frequency device, compact in structure, suitable for massproduction, and suitably applicable to a system of high-frequency such as microwave or millimeter wave.

SOLUTION: An antenna circuit board A is composed of an antenna element 3, a high-frequency line 4 which feeds an electric power to the antenna element 3, and a first dielectric board 2 where the high-frequency line 4 and the antenna element 3 are provided, and a high-frequency device circuit board B is composed of a second dielectric board 7 where a cavity 8 is provided, a high-frequency device 9 housed in the cavity 8, and a transmission line 11 which transmits signal to the high-frequency device 9, and a high-frequency package is equipped with the boards A and B, wherein the boards A and B are joined into one piece, and the high-frequency line 4 of the antenna circuit board A and the transmission line 11 of the high-frequency device circuit board B are connected together by electromagnetic coupling.

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